

### Absolute Maximum Ratings

| Symbol     | Parameter                            | Value      | Units |
|------------|--------------------------------------|------------|-------|
| $I_{PP}$   | Peak Current ( $t_p=8/20\mu s$ )     | 10         | A     |
| $P_{PK}$   | Peak Pulse Power ( $t_p=8/20\mu s$ ) | 150        | W     |
| $T_{OP}$   | Operating Temperature                | -40 to 125 | °C    |
| $T_{STOR}$ | Storage Temperature                  | -55 to 150 | °C    |

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

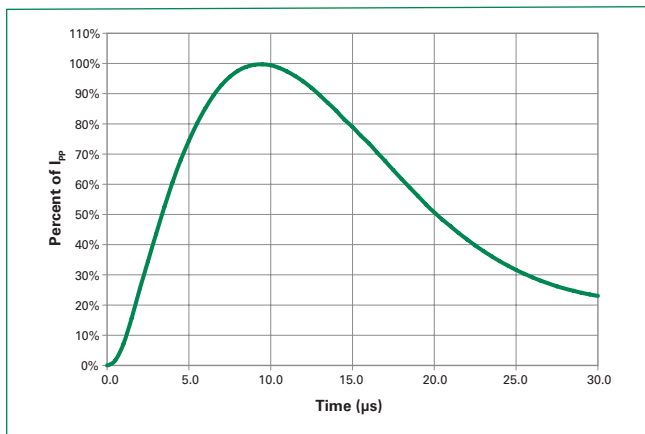
### Electrical Characteristics ( $T_{OP}=25^{\circ}C$ )

| Parameter                          | Symbol        | Test Conditions                             | Min      | Typ  | Max | Units    |
|------------------------------------|---------------|---|----------|------|-----|----------|
| Reverse Standoff Voltage           | $V_{RWM}$     | $I_R = 1\mu A$ , I/O to GND                 |          |      | 6   | V        |
| Breakdown Voltage                  | $V_{BR}$      | $I_R = 1mA$ , I/O to GND                    | 6        | 8.5  |     | V        |
| Reverse Leakage Current            | $I_{LEAK}$    | $V_R=5V$ , I/O to GND                       |          | 0.1  | 0.5 | $\mu A$  |
| Clamp Voltage <sup>1</sup>         | $V_C$         | $I_{PP}=5A$ , $t_p=8/20\mu s$ , I/O to GND  |          | 11.7 | 13  | V        |
|                                    |               | $I_{PP}=8A$ , $t_p=8/20\mu s$ , I/O to GND  |          | 12.5 | 14  | V        |
|                                    |               | $I_{PP}=10A$ , $t_p=8/20\mu s$ , I/O to GND |          | 13.2 | 15  | V        |
| Dynamic Resistance <sup>2</sup>    | $R_{DYN}$     | TLP, $t_p=100ns$ , I/O to GND               |          | 0.28 |     | $\Omega$ |
| ESD Withstand Voltage <sup>1</sup> | $V_{ESD}$     | IEC 61000-4-2 (Contact Discharge)           | $\pm 30$ |      |     | kV       |
|                                    |               | IEC 61000-4-2 (Air Discharge)               | $\pm 30$ |      |     | kV       |
| Diode Capacitance <sup>1</sup>     | $C_{I/O-GND}$ | Reverse Bias=0V, $f=1MHz$ , I/O to GND      |          | 1    | 3   | pF       |
|                                    | $C_{I/O-I/O}$ | Reverse Bias=0V, $f=1MHz$ , I/O to I/O      |          | 0.5  |     | pF       |

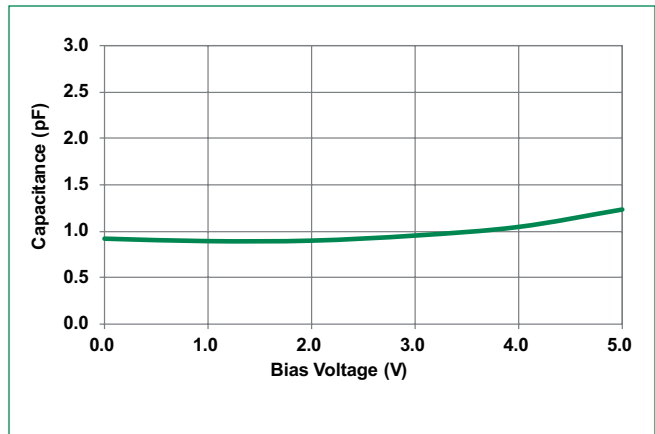
**Notes:**

- Parameter is guaranteed by design and/or component characterization.
- Transmission Line Pulse (TLP) test setting : Std.TDR(500), $t_p=100ns$ ,  $t_r=0.2ns$  ITLP and VTLP averaging window: start  $t_1=70ns$  to end  $t_2=80ns$

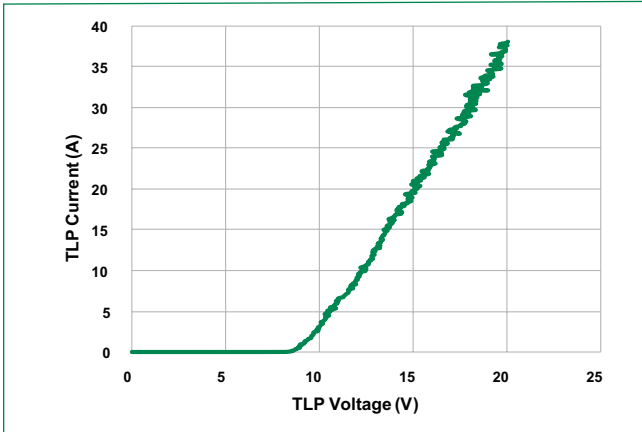
### 8/20 $\mu s$ Pulse Waveform



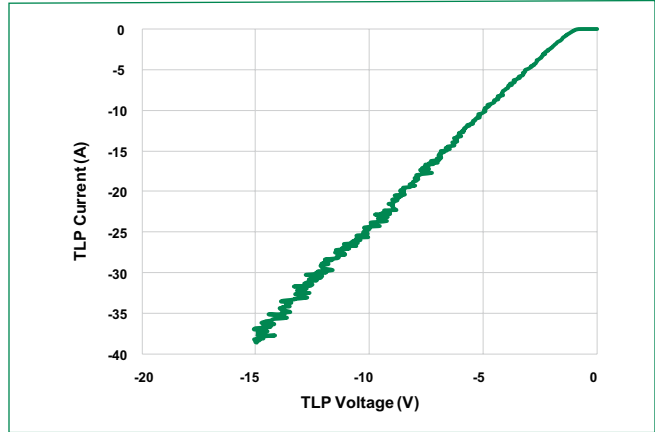
### Capacitance vs. Reverse Bias



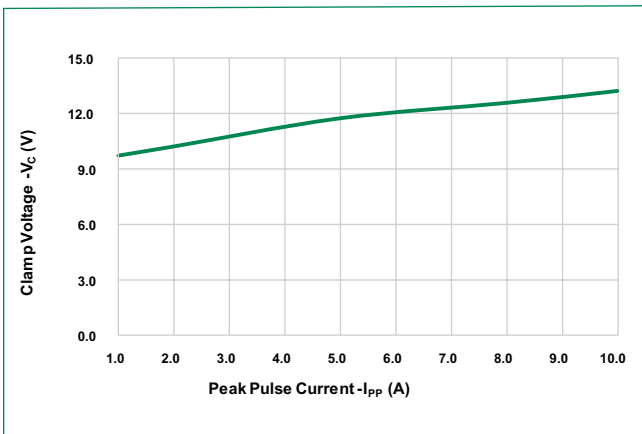
**Positive Transmission Line Pulsing (TLP) Plot**



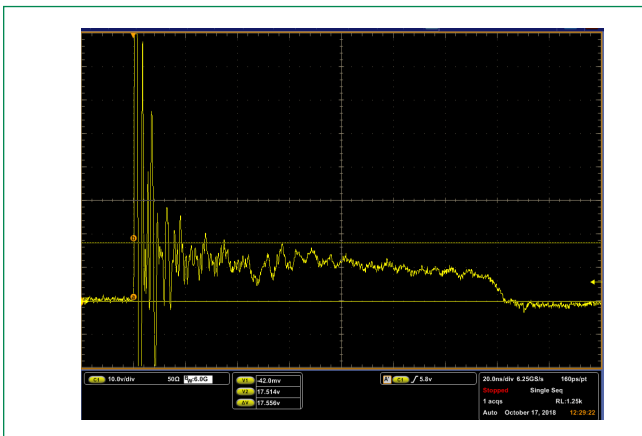
**Negative Transmission Line Pulsing (TLP) Plot**



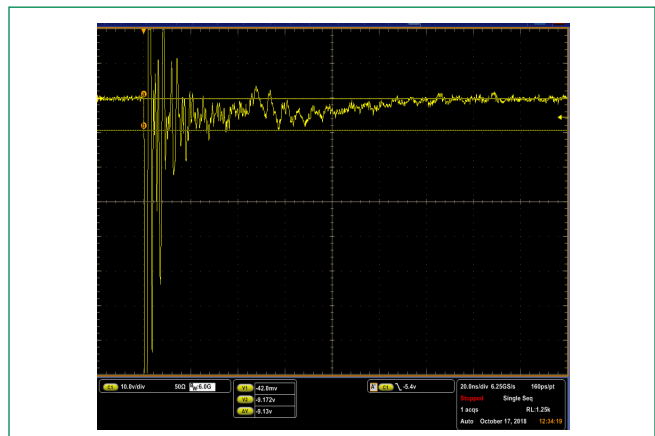
**Clamping Voltage vs. Peak Pulse Current**



**IEC 61000-4-2 +8 kV Contact ESD Clamping Voltage**

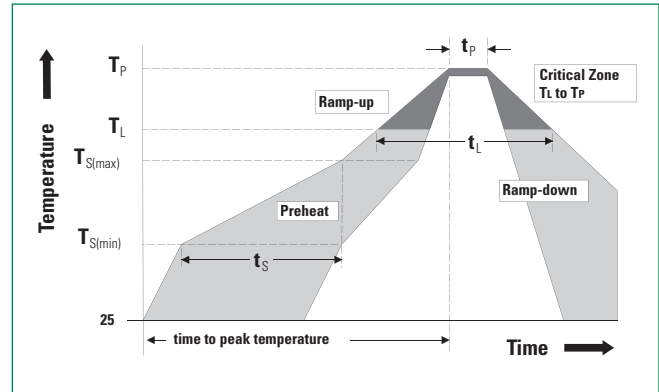


**IEC 61000-4-2 -8 kV Contact ESD Clamping Voltage**



### Soldering Parameters

|  |                                    |                         |
|--|------------------------------------|-------------------------|
| <b>Reflow Condition</b>  |                                    | Pb – Free assembly      |
| <b>Pre Heat</b>  | - Temperature Min ( $T_{s(min)}$ ) | 150°C                   |
|  | - Temperature Max ( $T_{s(max)}$ ) | 200°C                   |
|  | - Time (min to max) ( $t_s$ )      | 60 – 180 secs           |
| <b>Average ramp up rate (Liquidus) Temp (<math>T_L</math>) to peak</b> |                                    | 3°C/second max          |
| <b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>      |                                    | 3°C/second max          |
| <b>Reflow</b>  | - Temperature ( $T_L$ ) (Liquidus) | 217°C                   |
|  | - Temperature ( $t_L$ )            | 60 – 150 seconds        |
| <b>Peak Temperature (<math>T_p</math>)</b>                             |                                    | 260 <sup>+0/-5</sup> °C |
| <b>Time within 5°C of actual peak Temperature (<math>t_p</math>)</b>   |                                    | 20 – 40 seconds         |
| <b>Ramp-down Rate</b>  |                                    | 6°C/second max          |
| <b>Time 25°C to peak Temperature (<math>T_p</math>)</b>                |                                    | 8 minutes Max.          |
| <b>Do not exceed</b>   |                                    | 260°C                   |



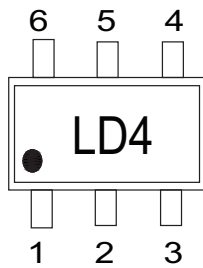
### Ordering Information

| Part Number  | Package | Min. Order Qty. |
|--------------|---------|-----------------|
| SRV05-4HTG-D | SOT23-6 | 3000            |

### Product Characteristics

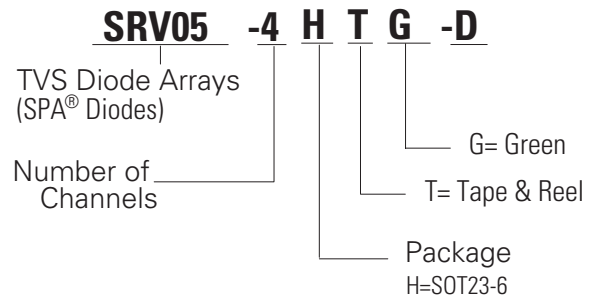
|                           |  |
|---------------------------|--|
| <b>Lead Plating</b>       | Matte Tin  |
| <b>Lead Material</b>      | Copper Alloy   |
| <b>Lead Conpanarity</b>   | 0.004 inches(0.102mm)                                  |
| <b>Substrate Material</b> | Silicon  |
| <b>Body Material</b>      | Molded Compound  |
| <b>Flammability</b>       | UL Recognized compound meeting flammability rating V-0 |

### Part Marking System

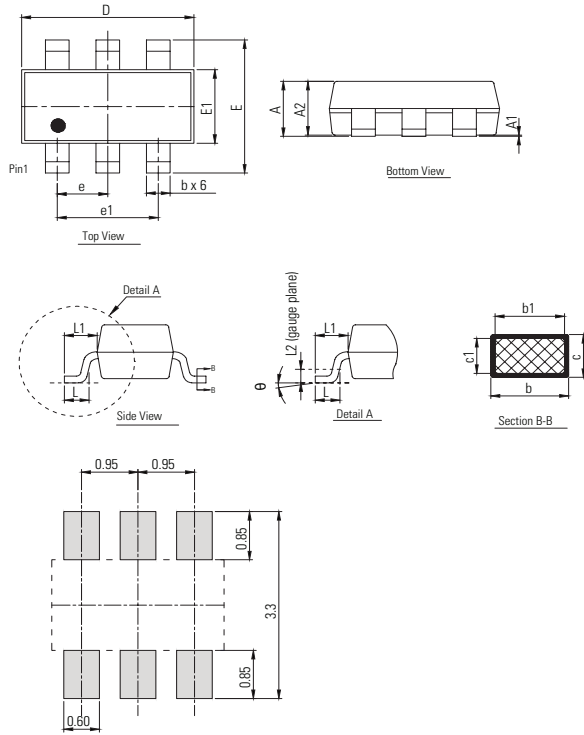


L : Part code  
D : Assembly code  
4 : Number of channel

### Part Numbering System



**Package Dimensions - SOT23-6**

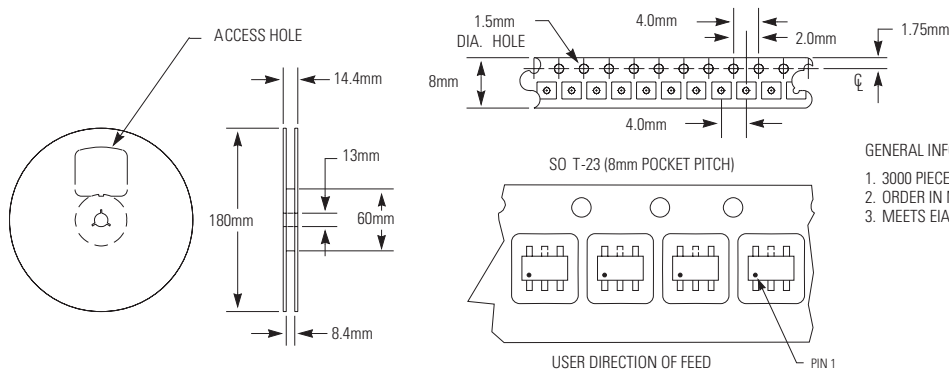


Recommended soldering pad layout (unit: mm)  
Drawing#: H02-B

| Symbol | Millimeters |      |      | Inches    |       |       |
|--------|-------------|------|------|-----------|-------|-------|
|        | Min         | Nom  | Max  | Min       | Nom   | Max   |
| A      | -           | -    | 1.45 | -         | -     | 0.057 |
| A1     | 0.00        | -    | 0.15 | 0.000     | -     | 0.006 |
| A2     | 0.90        | 1.15 | 1.30 | 0.035     | 0.045 | 0.051 |
| b      | 0.30        | -    | 0.50 | 0.012     | -     | 0.020 |
| b1     | 0.30        | 0.40 | 0.45 | 0.012     | 0.016 | 0.018 |
| c      | 0.08        | -    | 0.22 | 0.003     | -     | 0.009 |
| c1     | 0.08        | 0.13 | 0.20 | 0.003     | 0.005 | 0.008 |
| D      | 2.70        | 2.90 | 3.05 | 0.106     | 0.114 | 0.120 |
| E      | 2.60        | 2.80 | 3.00 | 0.102     | 0.110 | 0.118 |
| E1     | 1.45        | 1.60 | 1.75 | 0.057     | 0.063 | 0.069 |
| e      | 0.95 BSC    |      |      | 0.037 BSC |       |       |
| e1     | 1.90 BSC    |      |      | 0.075 BSC |       |       |
| L      | 0.30        | 0.50 | 0.60 | 0.012     | 0.020 | 0.024 |
| L1     | 0.60 REF    |      |      | 0.024 REF |       |       |
| L2     | 0.25 BSC    |      |      | 0.010 BSC |       |       |
| θ      | 0°          | 4°   | 8°   | 0°        | 4°    | 8°    |

**Embossed Carrier Tape & Reel Specification – SOT23-6**

**8mm TAPE AND REEL**



- GENERAL INFORMATION
- 3000 PIECES PER REEL.
  - ORDER IN MULTIPLES OF FULL REELS ONLY.
  - MEETS EIA-481 REVISION "A" SPECIFICATIONS.

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